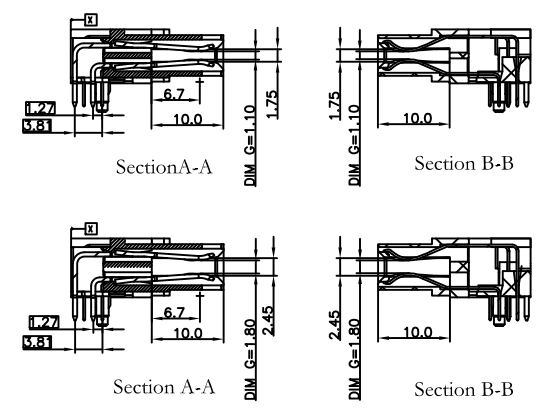
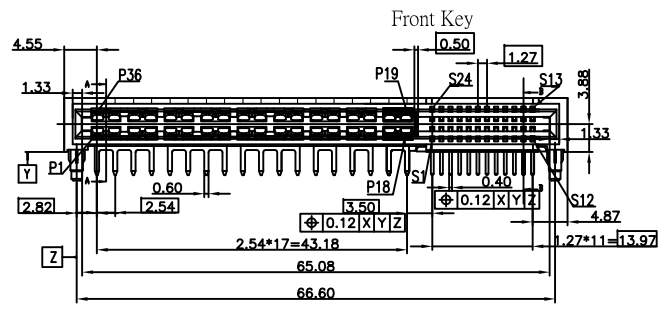
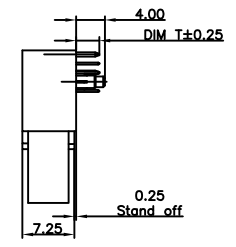
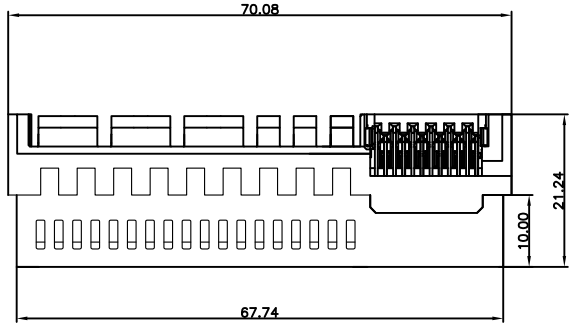


REV.	SPECIFICATION	ECN NO.	APPD.
X3			

**Material:**  
Housing: High Temperature Plastic UL94V-0 .  
Contacts: Copper Alloy.

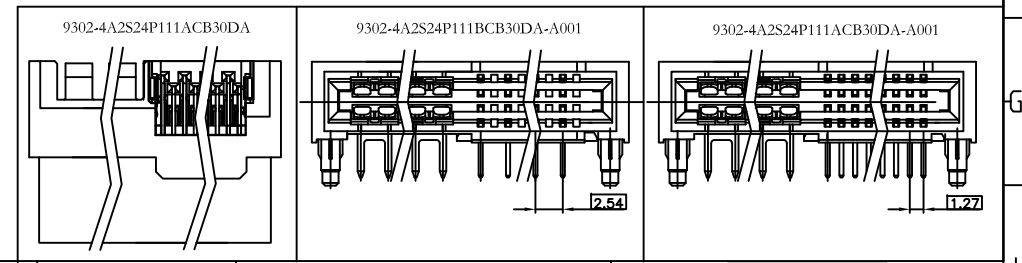
**Electrical Characteristics:**  
Current Rating: Signal Pin 1.5A.  
Power Pin 12.5A(UL).  
Dielectric Withstanding Voltage:  
Signal Pin DC 500V For 1 Minute.  
Power Pin DC 1000V For 1 Minute.  
Contact Resistance: Signal Pin 25mΩ max.  
Power Pin 0.6mΩ max.  
Insulator Resistance:Signal Pin 500MΩ min.at DC 500V  
Power Pin 5000MΩ min.at DC 500V  
Operating Temperature: -55°C~+105°C.  
**\*Rohs Compliant**



9302- 4 A2 S24 P 1 1 1 A CB30 D A

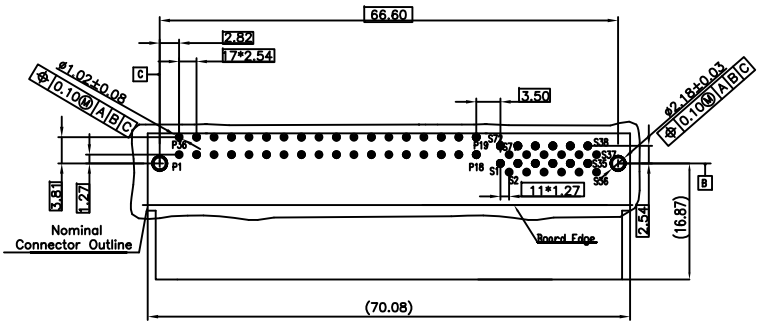
Series: 4:Female Right-angle, A2 :H12P06, Empty :Without Signal, Sxx:Signal Pin(08~72), N:W/O Post, P:With Post=4.00mm, B:With Post=3.40mm, 1: DIM T=3.25mm

A: Tray Package, D: Dip Type, CB30: Contact Au+Pd/Ni, Dip Tin 30 μ", B :Signal Pitch 2.54, A :Signal Pitch 1.27 (See Fig.2, See Fig.1), 1: With Front Key, 1: DIM G(GAP)1.10mm, 2: DIM G(GAP)1.80mm (Table A)

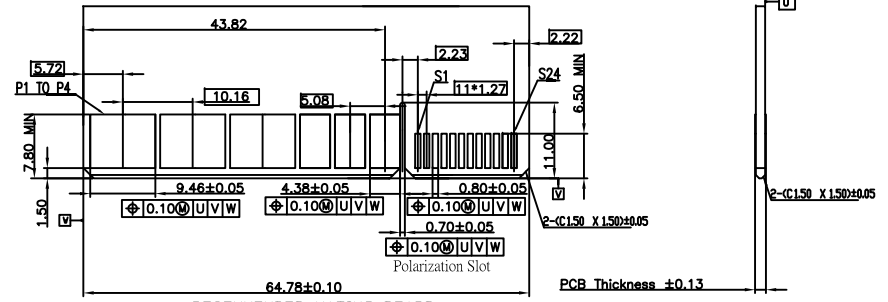


Tolerances X=±0.5 .X=±0.25 .XX=±0.15	Dwg.No.	9302-D0000-007		Title: 9302 Series High power and signal edge Card connector	 DUPIN ELECTRONIC(KUNSHAN) CO., LTD. P/N: 9302-4A2S24P111ACB30DA SHEET 1/2 Ver.No. X3	
	Projection					
	Unit	mm	Scale			1:1
	Drawn By	Alan 11/26'14				

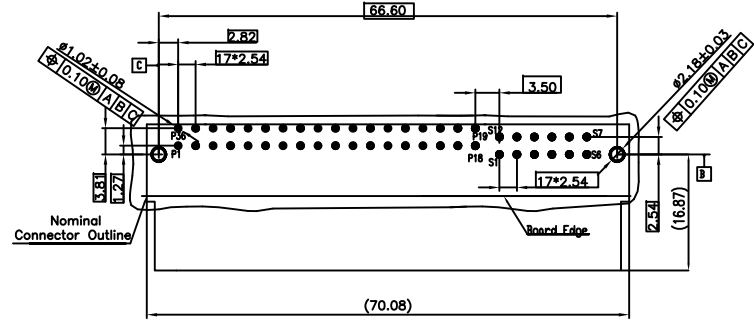
REV.	SPECIFICATION	ECN NO.	APPD.
X3			



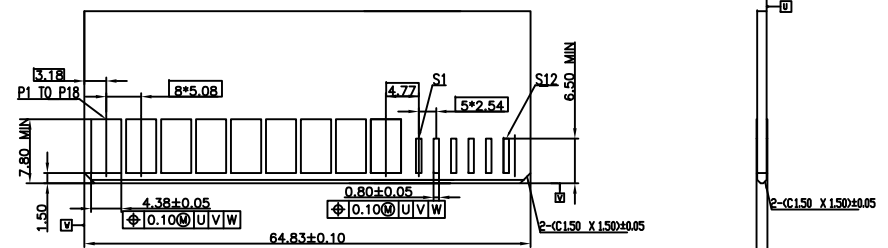
P.C.B. Layout  
(Tolerance: ±0.05)  
Fig.1



RECOMMENDED MATING BOARD  
FOOT PRINT



P.C.B. Layout  
(Tolerance: ±0.05)  
Fig.2



RECOMMENDED MATING BOARD  
FOOT PRINT

Dim G	PCB Thickness
1.10	1.57
1.80	2.30

Tolerances	Dwg.No.	9302-D000-007	Title:		<p>9302 Series High power and signal edge Card connector</p>	<p>DUPIIN ELECTRONIC(KUNSHAN) CO., LTD.</p>		
X=±0.5	Projection			P/N:			9302-4A2S24P111ACB30DA	
.X=±0.25	Unit	mm	Scale	1:1			SHEET	2/2
.XX=±0.15	Drawn By	Alan	Date	11/26'14			Ver.No.	X3